

CD54/74HC540, CD74HCT540, CD54/74HC541, CD54/74HCT541

High-Speed CMOS Logic Octal Buffer and Line Drivers, Three-State

Features

- 'HC540, CD74HCT540 Inverting
- 'HC541, 'HCT541 Non-Inverting
- Buffered Inputs
- Three-State Outputs
- Bus Line Driving Capability
- Typical Propagation Delay = 9ns at $V_{CC} = 5V$,
 $C_L = 15pF$, $T_A = 25^\circ C$
- Fanout (Over Temperature Range)
 - Standard Outputs 10 LSTTL Loads
 - Bus Driver Outputs 15 LSTTL Loads
- Wide Operating Temperature Range ... $-55^\circ C$ to $125^\circ C$
- Balanced Propagation Delay and Transition Times
- Significant Power Reduction Compared to LSTTL Logic ICs
- HC Types
 - 2V to 6V Operation
 - High Noise Immunity: $N_{IL} = 30\%$, $N_{IH} = 30\%$ of V_{CC} at $V_{CC} = 5V$
- HCT Types
 - 4.5V to 5.5V Operation
 - Direct LSTTL Input Logic Compatibility, $V_{IL} = 0.8V$ (Max), $V_{IH} = 2V$ (Min)
 - CMOS Input Compatibility, $I_I \leq 1\mu A$ at V_{OL} , V_{OH}

Description

The 'HC540 and CD74HCT540 are Inverting Octal Buffers and Line Drivers with Three-State Outputs and the capability to drive 15 LSTTL loads. The 'HC541 and 'HCT541 are Non-Inverting Octal Buffers and Line Drivers with Three-State Outputs that can drive 15 LSTTL loads. The Output Enables ($\overline{OE1}$) and ($\overline{OE2}$) control the Three-State Outputs. If either $\overline{OE1}$ or $\overline{OE2}$ is HIGH the outputs will be in the high impedance state. For data output $\overline{OE1}$ and $\overline{OE2}$ both must be LOW.

Ordering Information

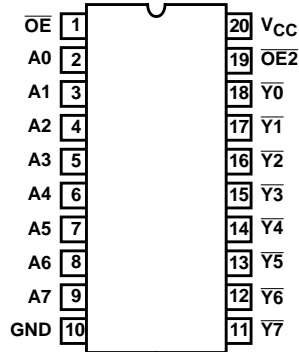
| PART NUMBER | TEMP. RANGE (°C) | PACKAGE |
|---------------|------------------|--------------|
| CD54HC540F3A | -55 to 125 | 20 Ld CERDIP |
| CD54HC541F3A | -55 to 125 | 20 Ld CERDIP |
| CD54HCT541F3A | -55 to 125 | 20 Ld CERDIP |
| CD74HC540E | -55 to 125 | 20 Ld PDIP |
| CD74HC540M | -55 to 125 | 20 Ld SOIC |
| CD74HC540M96 | -55 to 125 | 20 Ld SOIC |
| CD74HC541E | -55 to 125 | 20 Ld PDIP |
| CD74HC541M | -55 to 125 | 20 Ld SOIC |
| CD74HC541M96 | -55 to 125 | 20 Ld SOIC |
| CD74HC541PW | -55 to 125 | 20 Ld TSSOP |
| CD74HC541PWR | -55 to 125 | 20 Ld TSSOP |
| CD74HCT540E | -55 to 125 | 20 Ld PDIP |
| CD74HCT540M | -55 to 125 | 20 Ld SOIC |
| CD74HCT540M96 | -55 to 125 | 20 Ld SOIC |
| CD74HCT541E | -55 to 125 | 20 Ld PDIP |
| CD74HCT541M | -55 to 125 | 20 Ld SOIC |
| CD74HCT541M96 | -55 to 125 | 20 Ld SOIC |

NOTE: When ordering, use the entire part number. The suffix 96 denotes tape and reel.

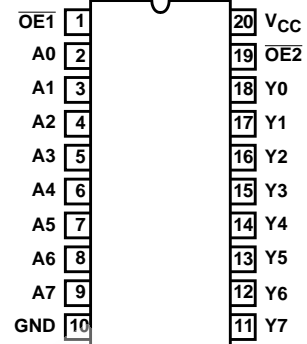
CD54/74HC540, CD74HCT540, CD54/74HC541, CD54/74HCT541

Pinouts

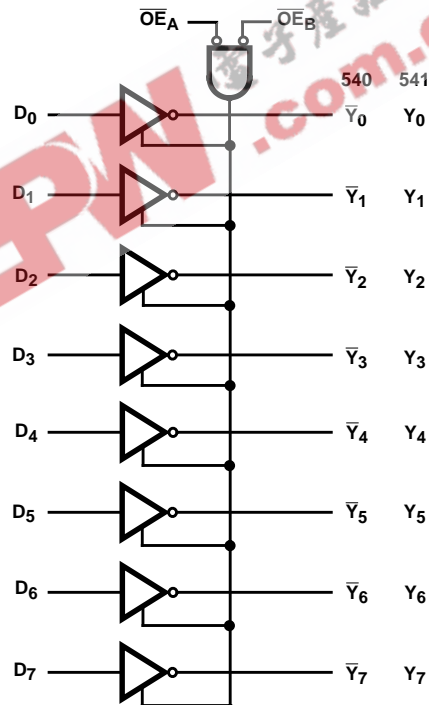
CD54HC540
(CERDIP)
CD74HC540, CD74HCT540
(PDIP, SOIC)
TOP VIEW



CD54HC541, CD54HCT541
(CERDIP)
CD74HC541
(PDIP, SOIC, TSSOP)
CD74HCT541
(PDIP, SOIC)
TOP VIEW



Functional Diagram



CD54/74HC540, CD74HCT540, CD54/74HC541, CD54/74HCT541

TRUTH TABLE

| INPUTS | | | OUTPUTS | |
|------------------|------------------|----|---------|-----|
| $\overline{OE1}$ | $\overline{OE2}$ | An | 540 | 541 |
| L | L | H | L | H |
| H | X | X | Z | Z |
| X | H | X | Z | Z |
| L | L | L | H | L |

H = HIGH Voltage Level
L = LOW Voltage Level
X = Don't Care
Z = High Impedance

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CD54/74HC540, CD74HCT540, CD54/74HC541, CD54/74HCT541

Absolute Maximum Ratings

| | |
|--|-------------|
| DC Supply Voltage, V_{CC} | -0.5V to 7V |
| DC Input Diode Current, I_{IK} | |
| For $V_I < -0.5V$ or $V_I > V_{CC} + 0.5V$ | $\pm 20mA$ |
| DC Output Diode Current, I_{OK} | |
| For $V_O < -0.5V$ or $V_O > V_{CC} + 0.5V$ | $\pm 20mA$ |
| DC Drain Current, per Output, I_O | |
| For $-0.5V < V_O < V_{CC} + 0.5V$ | $\pm 35mA$ |
| DC Output Source or Sink Current per Output Pin, I_O | |
| For $V_O > -0.5V$ or $V_O < V_{CC} + 0.5V$ | $\pm 25mA$ |
| DC V_{CC} or Ground Current, I_{CC} | $\pm 50mA$ |

Thermal Information

| | |
|--|---|
| Thermal Resistance (Typical, Note 1) | θ_{JA} ($^{\circ}C/W$) |
| E (PDIP) Package | 69 |
| M (SOIC) Package | 58 |
| PW (TSSOP) Package | 83 |
| Maximum Junction Temperature | $150^{\circ}C$ |
| Maximum Storage Temperature Range | $-65^{\circ}C$ to $150^{\circ}C$ |
| Maximum Lead Temperature (Soldering 10s) | $300^{\circ}C$ (SOIC - Lead Tips Only) |

Operating Conditions

| | |
|---|----------------------------------|
| Temperature Range, T_A | $-55^{\circ}C$ to $125^{\circ}C$ |
| Supply Voltage Range, V_{CC} | |
| HC Types | .2V to 6V |
| HCT Types | 4.5V to 5.5V |
| DC Input or Output Voltage, V_I , V_O | 0V to V_{CC} |
| Input Rise and Fall Time | |
| 2V | 1000ns (Max) |
| 4.5V | 500ns (Max) |
| 6V | 400ns (Max) |

CAUTION: Stresses above those listed in "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress only rating and operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied.

NOTE:

- The package thermal impedance is calculated in accordance with JEDEC 51-7.

DC Electrical Specifications

| PARAMETER | SYMBOL | TEST CONDITIONS | | V_{CC} (V) | 25 $^{\circ}C$ | | | -40 $^{\circ}C$ TO 85 $^{\circ}C$ | | -55 $^{\circ}C$ TO 125 $^{\circ}C$ | | UNITS | |
|---|----------|----------------------|------------|--------------|----------------|------|------|-----------------------------------|------|------------------------------------|------|---------|---------|
| | | V_I (V) | I_O (mA) | | MIN | TYP | MAX | MIN | MAX | MIN | MAX | | |
| HC TYPES | | | | | | | | | | | | | |
| High Level Input Voltage | V_{IH} | - | - | 2 | 1.5 | - | - | 1.5 | - | 1.5 | - | V | |
| | | | | 4.5 | 3.15 | - | - | 3.15 | - | 3.15 | - | V | |
| | | | | 6 | 4.2 | - | - | 4.2 | - | 4.2 | - | V | |
| Low Level Input Voltage | V_{IL} | - | - | 2 | - | - | 0.5 | - | 0.5 | - | 0.5 | V | |
| | | | | 4.5 | - | - | 1.35 | - | 1.35 | - | 1.35 | V | |
| | | | | 6 | - | - | 1.8 | - | 1.8 | - | 1.8 | V | |
| High Level Output Voltage CMOS Loads | V_{OH} | V_{IH} or V_{IL} | -0.02 | -0.02 | 2 | 1.9 | - | - | 1.9 | - | 1.9 | - | V |
| | | | -0.02 | -0.02 | 4.5 | 4.4 | - | - | 4.4 | - | 4.4 | - | V |
| | | | -0.02 | -0.02 | 6 | 5.9 | - | - | 5.9 | - | 5.9 | - | V |
| High Level Output Voltage TTL Loads | V_{OH} | V_{IH} or V_{IL} | - | - | - | - | - | - | - | - | - | V | |
| | | | -6 | -6 | 4.5 | 3.98 | - | - | 3.84 | - | 3.7 | - | V |
| | | | -7.8 | -7.8 | 6 | 5.48 | - | - | 5.34 | - | 5.2 | - | V |
| Low Level Output Voltage CMOS Loads | V_{OL} | V_{IH} or V_{IL} | 0.02 | 0.02 | 2 | - | - | 0.1 | - | 0.1 | - | 0.1 | V |
| | | | 0.02 | 0.02 | 4.5 | - | - | 0.1 | - | 0.1 | - | 0.1 | V |
| | | | 0.02 | 0.02 | 6 | - | - | 0.1 | - | 0.1 | - | 0.1 | V |
| Low Level Output Voltage TTL Loads | V_{OL} | V_{IH} or V_{IL} | - | - | - | - | - | - | - | - | - | V | |
| | | | 6 | 6 | 4.5 | - | - | 0.26 | - | 0.33 | - | 0.4 | V |
| | | | 7.8 | 7.8 | 6 | - | - | 0.26 | - | 0.33 | - | 0.4 | V |
| Input Leakage Current | I_I | V_{CC} or GND | - | - | 6 | - | - | ± 0.1 | - | ± 1 | - | ± 1 | μA |

CD54/74HC540, CD74HCT540, CD54/74HC541, CD54/74HCT541

DC Electrical Specifications (Continued)

| PARAMETER | SYMBOL | TEST CONDITIONS | | V _{CC} (V) | 25°C | | | -40°C TO 85°C | | -55°C TO 125°C | | UNITS |
|--|---------------------------|------------------------------------|---|---------------------|------|-----|------|---------------|------|----------------|-----|-------|
| | | V _I (V) | I _O (mA) | | MIN | TYP | MAX | MIN | MAX | MIN | MAX | |
| Quiescent Device Current | I _{CC} | V _{CC} or GND | 0 | 6 | - | - | 8 | - | 80 | - | 160 | μA |
| Three- State Leakage Current | I _{OZ} | V _{IL} or V _{IH} | V _O = V _{CC} or GND | 6 | - | - | ±0.5 | - | ±5.0 | - | ±10 | μA |
| HCT TYPES | | | | | | | | | | | | |
| High Level Input Voltage | V _{IH} | - | - | 4.5 to 5.5 | 2 | - | - | 2 | - | 2 | - | V |
| Low Level Input Voltage | V _{IL} | - | - | 4.5 to 5.5 | - | - | 0.8 | - | 0.8 | - | 0.8 | V |
| High Level Output Voltage CMOS Loads | V _{OH} | V _{IH} or V _{IL} | -0.02 | 4.5 | 4.4 | - | - | 4.4 | - | 4.4 | - | V |
| High Level Output Voltage TTL Loads | | | -6 | 4.5 | 3.98 | - | - | 3.84 | - | 3.7 | - | V |
| Low Level Output Voltage CMOS Loads | V _{OL} | V _{IH} or V _{IL} | 0.02 | 4.5 | - | - | 0.1 | - | 0.1 | - | 0.1 | V |
| Low Level Output Voltage TTL Loads | | | 6 | 4.5 | - | - | 0.26 | - | 0.33 | - | 0.4 | V |
| Input Leakage Current | I _I | V _{CC} and GND | 0 | 5.5 | - | - | ±0.1 | - | ±1 | - | ±1 | μA |
| Quiescent Device Current | I _{CC} | V _{CC} or GND | 0 | 5.5 | - | - | 8 | - | 80 | - | 160 | μA |
| Three- State Leakage Current | I _{OZ} | V _{IL} or V _{IH} | V _O = V _{CC} or GND | 5.5 | - | - | ±0.5 | - | ±5.0 | - | ±10 | μA |
| Additional Quiescent Device Current Per Input Pin: 1 Unit Load | ΔI _{CC} (Note 2) | V _{CC} -2.1 | - | 4.5 to 5.5 | - | 100 | 360 | - | 450 | - | 490 | μA |

NOTE:

- For dual-supply systems theoretical worst case (V_I = 2.4V, V_{CC} = 5.5V) specification is 1.8mA.

HCT Input Loading Table

| INPUT | UNIT LOADS | |
|------------------|------------|--------|
| | HCT540 | HCT541 |
| A0 - A7 | 1 | 0.4 |
| $\overline{OE}2$ | 0.75 | 0.75 |
| $\overline{OE}1$ | 1.15 | 1.15 |

NOTE: Unit Load is ΔI_{CC} limit specific in DC Electrical Specifications Table, e.g., 360μA max. at 25°C.

CD54/74HC540, CD74HCT540, CD54/74HC541, CD54/74HCT541

Switching Specifications $C_L = 50\text{pF}$, Input $t_r, t_f = 6\text{ns}$

| PARAMETER | SYMBOL | TEST CONDITIONS | V_{CC} (V) | 25°C | | | -40°C TO 85°C | | -55°C TO 125°C | | UNITS |
|---|--------------------|---------------------|--------------|------|-----|-----|---------------|-----|----------------|-----|-------|
| | | | | MIN | TYP | MAX | MIN | MAX | MIN | MAX | |
| HC TYPES | | | | | | | | | | | |
| Propagation Delay Data to Outputs (540) | t_{PLH}, t_{PHL} | $C_L = 50\text{pF}$ | 2 | - | - | 110 | - | 140 | - | 165 | ns |
| | | | 4.5 | - | - | 22 | - | 28 | - | 33 | ns |
| | | $C_L = 15\text{pF}$ | 5 | - | 9 | - | - | - | - | - | ns |
| | | $C_L = 50\text{pF}$ | 6 | - | - | 19 | - | 24 | - | 28 | ns |
| Data to Outputs (541) | t_{PLZ}, t_{PHZ} | $C_L = 50\text{pF}$ | 2 | - | - | 115 | - | 145 | - | 175 | ns |
| | | | 4.5 | - | - | 23 | - | 29 | - | 35 | ns |
| | | $C_L = 15\text{pF}$ | 5 | - | 9 | - | - | - | - | - | ns |
| | | $C_L = 50\text{pF}$ | 6 | - | - | 20 | - | 25 | - | 30 | ns |
| Output Enable and Disable to Outputs (540) | t_{PLZ}, t_{PHZ} | $C_L = 50\text{pF}$ | 2 | - | - | 160 | - | 200 | - | 240 | ns |
| | | | 4.5 | - | - | 32 | - | 40 | - | 48 | ns |
| | | $C_L = 15\text{pF}$ | 5 | - | 13 | - | - | - | - | - | ns |
| | | $C_L = 50\text{pF}$ | 6 | - | - | 27 | - | 34 | - | 41 | ns |
| Output Enable and Disable to Outputs (541) | t_{PLZ}, t_{PHZ} | $C_L = 50\text{pF}$ | 2 | - | - | 160 | - | 200 | - | 240 | ns |
| | | | 4.5 | - | - | 32 | - | 40 | - | 48 | ns |
| | | $C_L = 15\text{pF}$ | 5 | - | 14 | - | - | - | - | - | ns |
| | | $C_L = 50\text{pF}$ | 6 | - | - | 23 | - | 29 | - | 35 | ns |
| Output Transition Time | t_{THL}, t_{TLH} | $C_L = 50\text{pF}$ | 2 | - | - | 60 | - | 75 | - | 90 | ns |
| | | | 4.5 | - | - | 12 | - | 15 | - | 18 | ns |
| | | | 6 | - | - | 10 | - | 13 | - | 15 | ns |
| Input Capacitance | C_I | $C_L = 50\text{pF}$ | - | 10 | - | 10 | - | 10 | - | 10 | pF |
| Three-State Output Capacitance | C_O | - | - | 20 | - | 20 | - | 20 | - | 20 | pF |
| Power Dissipation Capacitance (Notes 3, 4) (540) | C_{PD} | $C_L = 15\text{pF}$ | 5 | - | 50 | - | - | - | - | - | pF |
| Power Dissipation Capacitance (Notes 3, 4) (541) | C_{PD} | $C_L = 15\text{pF}$ | 5 | - | 48 | - | - | - | - | - | pF |
| HCT TYPES | | | | | | | | | | | |
| Propagation Delay Data to Outputs (540) | t_{PHL}, t_{PLH} | $C_L = 50\text{pF}$ | 4.5 | - | - | 24 | - | 30 | - | 36 | ns |
| | | $C_L = 15\text{pF}$ | 5 | - | 9 | - | - | - | - | - | ns |
| Data to Outputs (541) | t_{PHL}, t_{PLH} | $C_L = 50\text{pF}$ | 4.5 | - | - | 28 | - | 35 | - | 42 | ns |
| | | $C_L = 15\text{pF}$ | 5 | - | 11 | - | - | - | - | - | ns |
| Output Enable and Disable to Outputs (540, 541) | t_{PLZ}, t_{PHZ} | $C_L = 50\text{pF}$ | 4.5 | - | - | 35 | - | 44 | - | 53 | ns |
| | | $C_L = 15\text{pF}$ | 5 | - | 14 | - | - | - | - | - | ns |
| Output Transition Time | t_{TLH}, t_{THL} | $C_L = 50\text{pF}$ | 4.5 | - | - | 12 | - | 15 | - | 18 | ns |
| Input Capacitance | C_I | $C_L = 50\text{pF}$ | - | 10 | - | 10 | - | 10 | - | 10 | pF |

CD54/74HC540, CD74HCT540, CD54/74HC541, CD54/74HCT541

Switching Specifications $C_L = 50\text{pF}$, Input $t_r, t_f = 6\text{ns}$ (Continued)

| PARAMETER | SYMBOL | TEST CONDITIONS | V_{CC} (V) | 25°C | | | -40°C TO 85°C | | -55°C TO 125°C | | UNITS |
|---|----------|---------------------|--------------|------|-----|-----|---------------|-----|----------------|-----|-------|
| | | | | MIN | TYP | MAX | MIN | MAX | MIN | MAX | |
| Three-State Output Capacitance | C_O | - | - | 20 | - | 20 | - | 20 | - | 20 | pF |
| Power Dissipation Capacitance (Notes 3, 4) (540, 541) | C_{PD} | $C_L = 15\text{pF}$ | 5 | - | 55 | - | - | - | - | - | pF |

NOTES:

3. C_{PD} is used to determine the dynamic power consumption, per channel.
4. $P_D = V_{CC}^2 f_i (C_{PD} + C_L)$ where f_i = Input Frequency, C_L = Output Load Capacitance, V_{CC} = Supply Voltage.

Test Circuits and Waveforms

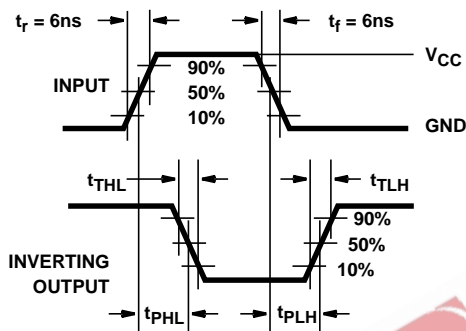


FIGURE 1. HC TRANSITION TIMES AND PROPAGATION DELAY TIMES, COMBINATION LOGIC

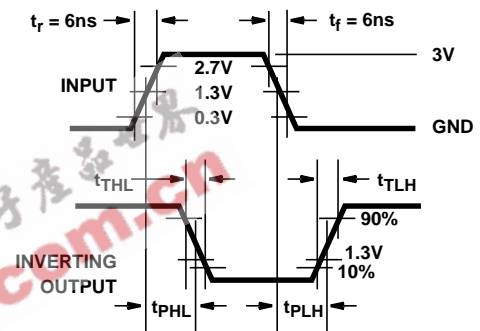


FIGURE 2. HCT TRANSITION TIMES AND PROPAGATION DELAY TIMES, COMBINATION LOGIC

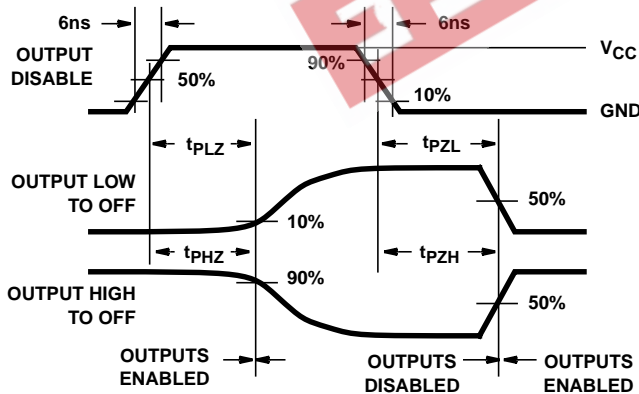


FIGURE 3. HC THREE-STATE PROPAGATION DELAY WAVEFORM

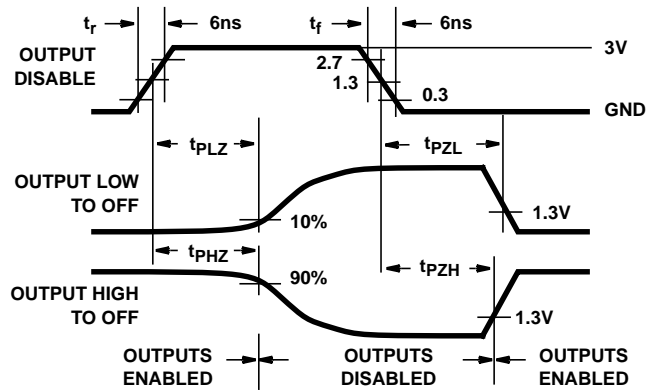
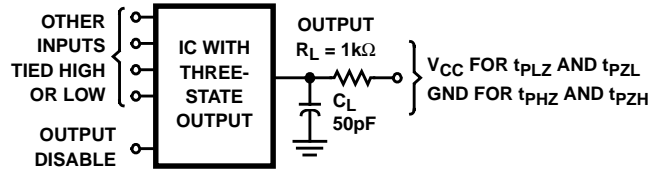


FIGURE 4. HCT THREE-STATE PROPAGATION DELAY WAVEFORM

Test Circuits and Waveforms (Continued)



NOTE: Open drain waveforms t_{PLZ} and t_{PZL} are the same as those for three-state shown on the left. The test circuit is Output $R_L = 1k\Omega$ to V_{CC} , $C_L = 50pF$.

FIGURE 5. HC AND HCT THREE-STATE PROPAGATION DELAY TEST CIRCUIT

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PACKAGING INFORMATION

| Orderable Device | Status ⁽¹⁾ | Package Type | Package Drawing | Pins | Package Qty | Eco Plan ⁽²⁾ | Lead/Ball Finish | MSL Peak Temp ⁽³⁾ |
|------------------|-----------------------|--------------|-----------------|------|-------------|-------------------------|------------------|------------------------------|
| CD54HC540F3A | ACTIVE | CDIP | J | 20 | 1 | TBD | A42 SNPB | N / A for Pkg Type |
| CD54HC541F | ACTIVE | CDIP | J | 20 | 1 | TBD | A42 SNPB | N / A for Pkg Type |
| CD54HC541F3A | ACTIVE | CDIP | J | 20 | 1 | TBD | A42 SNPB | N / A for Pkg Type |
| CD54HCT541F | ACTIVE | CDIP | J | 20 | 1 | TBD | A42 SNPB | N / A for Pkg Type |
| CD54HCT541F3A | ACTIVE | CDIP | J | 20 | 1 | TBD | A42 SNPB | N / A for Pkg Type |
| CD74HC540E | ACTIVE | PDIP | N | 20 | 20 | Pb-Free (RoHS) | CU NIPDAU | N / A for Pkg Type |
| CD74HC540EE4 | ACTIVE | PDIP | N | 20 | 20 | Pb-Free (RoHS) | CU NIPDAU | N / A for Pkg Type |
| CD74HC540M | ACTIVE | SOIC | DW | 20 | 25 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| CD74HC540M96 | ACTIVE | SOIC | DW | 20 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| CD74HC540M96E4 | ACTIVE | SOIC | DW | 20 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| CD74HC540M96G4 | ACTIVE | SOIC | DW | 20 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| CD74HC540ME4 | ACTIVE | SOIC | DW | 20 | 25 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| CD74HC540MG4 | ACTIVE | SOIC | DW | 20 | 25 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| CD74HC541E | ACTIVE | PDIP | N | 20 | 20 | Pb-Free (RoHS) | CU NIPDAU | N / A for Pkg Type |
| CD74HC541EE4 | ACTIVE | PDIP | N | 20 | 20 | Pb-Free (RoHS) | CU NIPDAU | N / A for Pkg Type |
| CD74HC541M | ACTIVE | SOIC | DW | 20 | 25 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| CD74HC541M96 | ACTIVE | SOIC | DW | 20 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| CD74HC541M96E4 | ACTIVE | SOIC | DW | 20 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| CD74HC541M96G4 | ACTIVE | SOIC | DW | 20 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| CD74HC541MG4 | ACTIVE | SOIC | DW | 20 | 25 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| CD74HC541PW | ACTIVE | TSSOP | PW | 20 | 70 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| CD74HC541PWE4 | ACTIVE | TSSOP | PW | 20 | 70 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| CD74HC541PWG4 | ACTIVE | TSSOP | PW | 20 | 70 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| CD74HC541PWR | ACTIVE | TSSOP | PW | 20 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| CD74HC541PWRE4 | ACTIVE | TSSOP | PW | 20 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| CD74HC541PWG4 | ACTIVE | TSSOP | PW | 20 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| CD74HC541SM | OBSOLETE | SSOP | DB | 20 | | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |

| Orderable Device | Status ⁽¹⁾ | Package Type | Package Drawing | Pins | Package Qty | Eco Plan ⁽²⁾ | Lead/Ball Finish | MSL Peak Temp ⁽³⁾ |
|------------------|-----------------------|--------------|-----------------|------|-------------|-------------------------|------------------|------------------------------|
| CD74HCT540E | ACTIVE | PDIP | N | 20 | 20 | Pb-Free (RoHS) | CU NIPDAU | N / A for Pkg Type |
| CD74HCT540EE4 | ACTIVE | PDIP | N | 20 | 20 | Pb-Free (RoHS) | CU NIPDAU | N / A for Pkg Type |
| CD74HCT540M | ACTIVE | SOIC | DW | 20 | 25 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| CD74HCT540M96 | ACTIVE | SOIC | DW | 20 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| CD74HCT540M96E4 | ACTIVE | SOIC | DW | 20 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| CD74HCT540M96G4 | ACTIVE | SOIC | DW | 20 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| CD74HCT540MG4 | ACTIVE | SOIC | DW | 20 | 25 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| CD74HCT541E | ACTIVE | PDIP | N | 20 | 20 | Pb-Free (RoHS) | CU NIPDAU | N / A for Pkg Type |
| CD74HCT541EE4 | ACTIVE | PDIP | N | 20 | 20 | Pb-Free (RoHS) | CU NIPDAU | N / A for Pkg Type |
| CD74HCT541M | ACTIVE | SOIC | DW | 20 | 25 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| CD74HCT541M96 | ACTIVE | SOIC | DW | 20 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| CD74HCT541M96E4 | ACTIVE | SOIC | DW | 20 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| CD74HCT541M96G4 | ACTIVE | SOIC | DW | 20 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| CD74HCT541ME4 | ACTIVE | SOIC | DW | 20 | 25 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| CD74HCT541MG4 | ACTIVE | SOIC | DW | 20 | 25 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

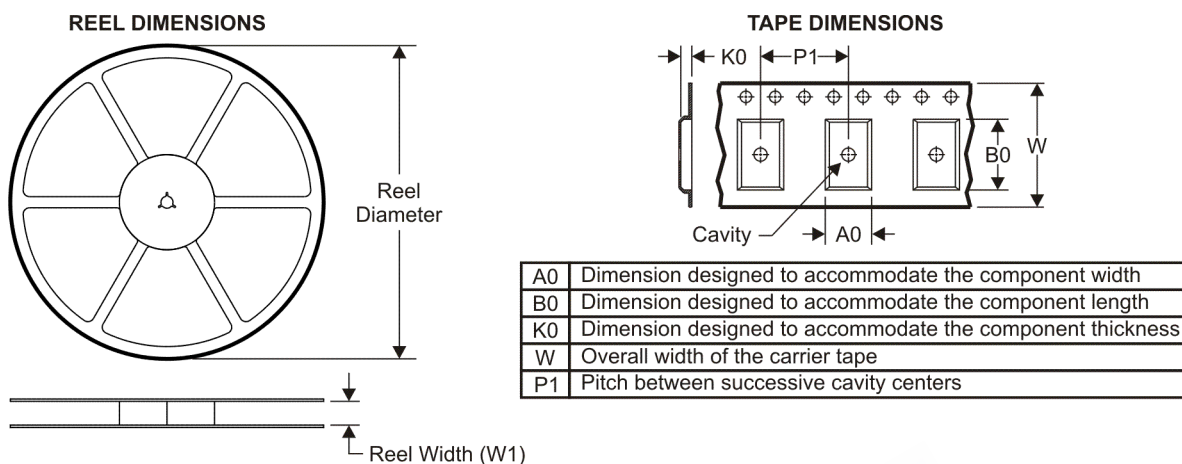
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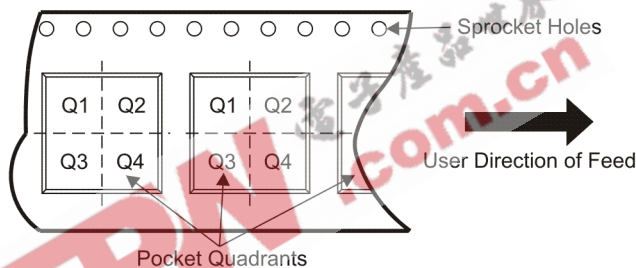
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TAPE AND REEL INFORMATION



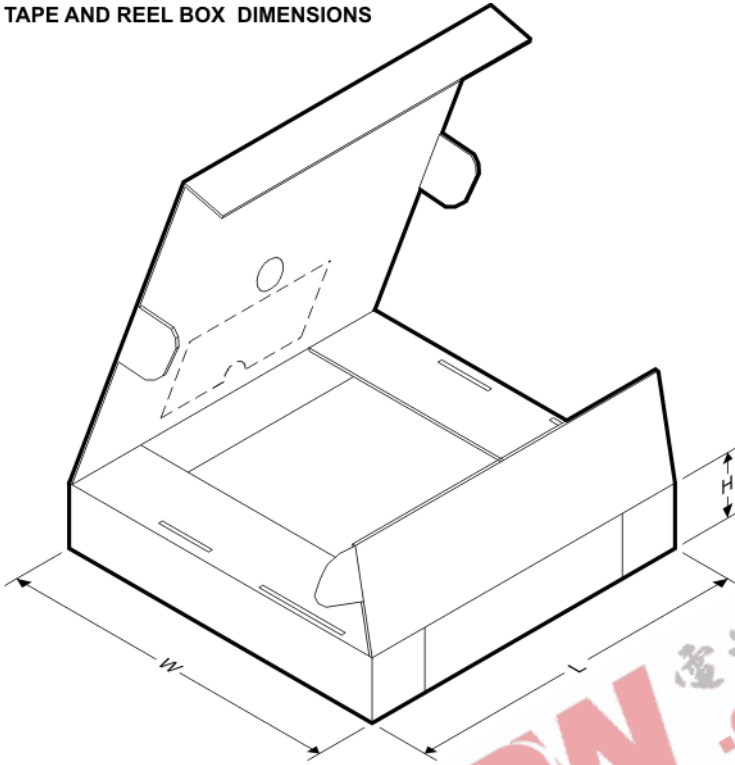
QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

| Device | Package Type | Package Drawing | Pins | SPQ | Reel Diameter (mm) | Reel Width W1 (mm) | A0 (mm) | B0 (mm) | K0 (mm) | P1 (mm) | W (mm) | Pin1 Quadra |
|---------------|--------------|-----------------|------|------|--------------------|--------------------|---------|---------|---------|---------|--------|-------------|
| CD74HC540M96 | SOIC | DW | 20 | 2000 | 330.0 | 24.4 | 10.8 | 13.0 | 2.7 | 12.0 | 24.0 | Q1 |
| CD74HC541M96 | SOIC | DW | 20 | 2000 | 330.0 | 24.4 | 10.8 | 13.0 | 2.7 | 12.0 | 24.0 | Q1 |
| CD74HC541PWR | TSSOP | PW | 20 | 2000 | 330.0 | 16.4 | 6.95 | 7.1 | 1.6 | 8.0 | 16.0 | Q1 |
| CD74HCT540M96 | SOIC | DW | 20 | 2000 | 330.0 | 24.4 | 10.8 | 13.0 | 2.7 | 12.0 | 24.0 | Q1 |
| CD74HCT541M96 | SOIC | DW | 20 | 2000 | 330.0 | 24.4 | 10.8 | 13.0 | 2.7 | 12.0 | 24.0 | Q1 |

TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

| Device | Package Type | Package Drawing | Pins | SPQ | Length (mm) | Width (mm) | Height (mm) |
|---------------|--------------|-----------------|------|------|-------------|------------|-------------|
| CD74HC540M96 | SOIC | DW | 20 | 2000 | 346.0 | 346.0 | 41.0 |
| CD74HC541M96 | SOIC | DW | 20 | 2000 | 346.0 | 346.0 | 41.0 |
| CD74HC541PWR | TSSOP | PW | 20 | 2000 | 346.0 | 346.0 | 33.0 |
| CD74HCT540M96 | SOIC | DW | 20 | 2000 | 346.0 | 346.0 | 41.0 |
| CD74HCT541M96 | SOIC | DW | 20 | 2000 | 346.0 | 346.0 | 41.0 |

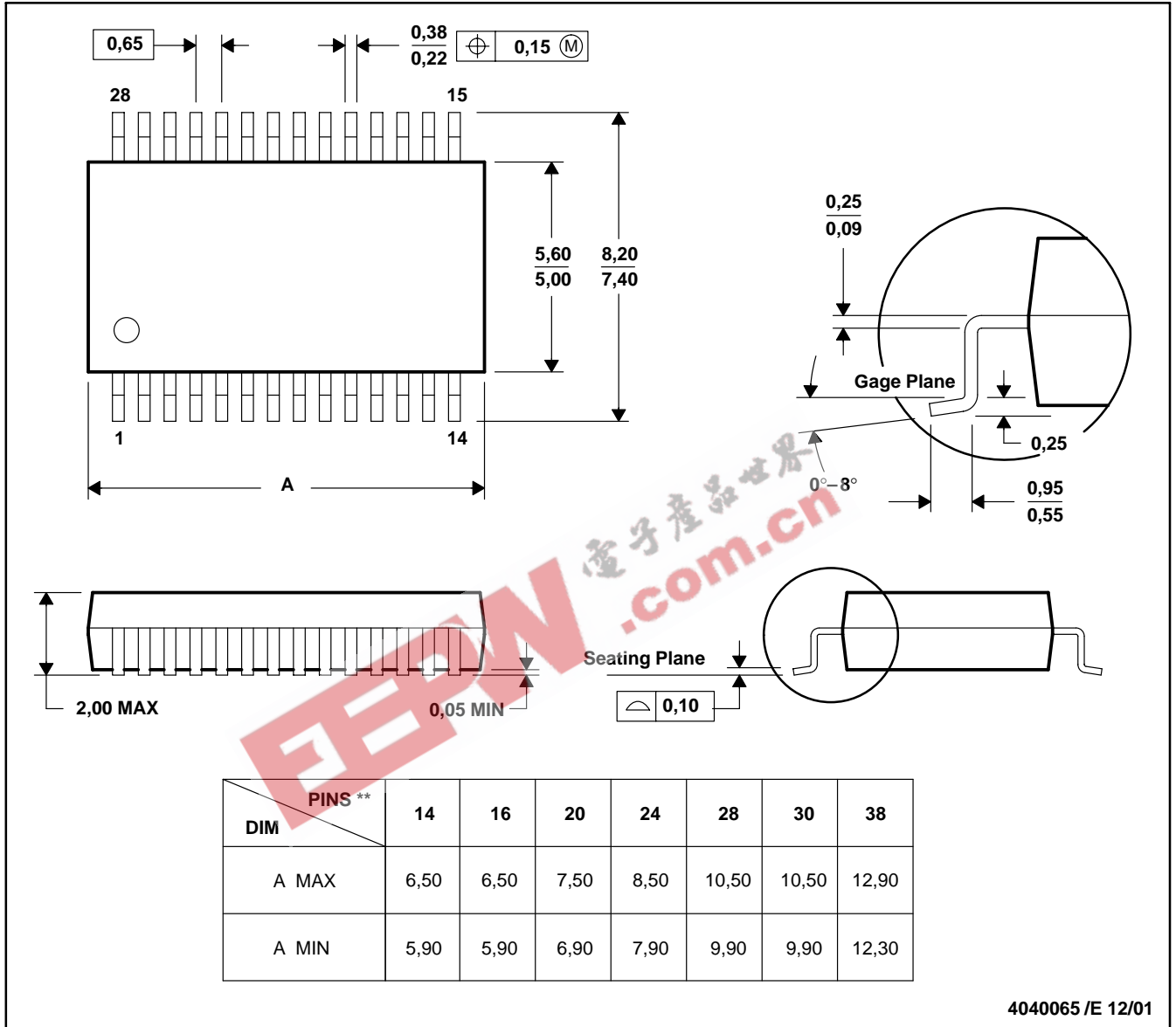
MECHANICAL DATA

MSS0002E – JANUARY 1995 – REVISED DECEMBER 2001

DB (R-PDSO-G**)

PLASTIC SMALL-OUTLINE

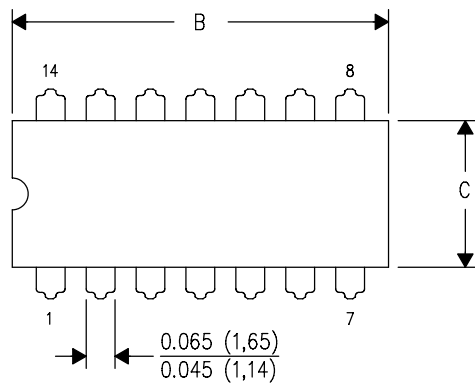
28 PINS SHOWN



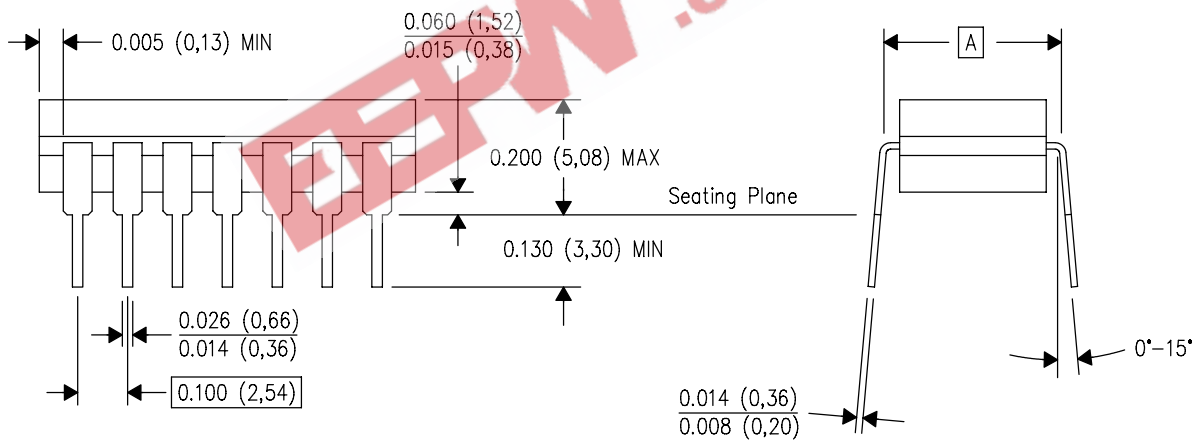
- NOTES: A. All linear dimensions are in millimeters.
 B. This drawing is subject to change without notice.
 C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.
 D. Falls within JEDEC MO-150

J (R-GDIP-T**)
14 LEADS SHOWN

CERAMIC DUAL IN-LINE PACKAGE



| DIM \ PINS ** | 14 | 16 | 18 | 20 |
|---------------|------------------------|------------------------|------------------------|------------------------|
| A | 0.300 (7,62) BSC | 0.300 (7,62) BSC | 0.300 (7,62) BSC | 0.300 (7,62) BSC |
| B MAX | 0.785 (19,94) | .840 (21,34) | 0.960 (24,38) | 1.060 (26,92) |
| B MIN | — | — | — | — |
| C MAX | 0.300 (7,62) | 0.300 (7,62) | 0.310 (7,87) | 0.300 (7,62) |
| C MIN | 0.245 (6,22) | 0.245 (6,22) | 0.220 (5,59) | 0.245 (6,22) |



4040083/F 03/03

- NOTES:
- All linear dimensions are in inches (millimeters).
 - This drawing is subject to change without notice.
 - This package is hermetically sealed with a ceramic lid using glass frit.
 - Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
 - Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

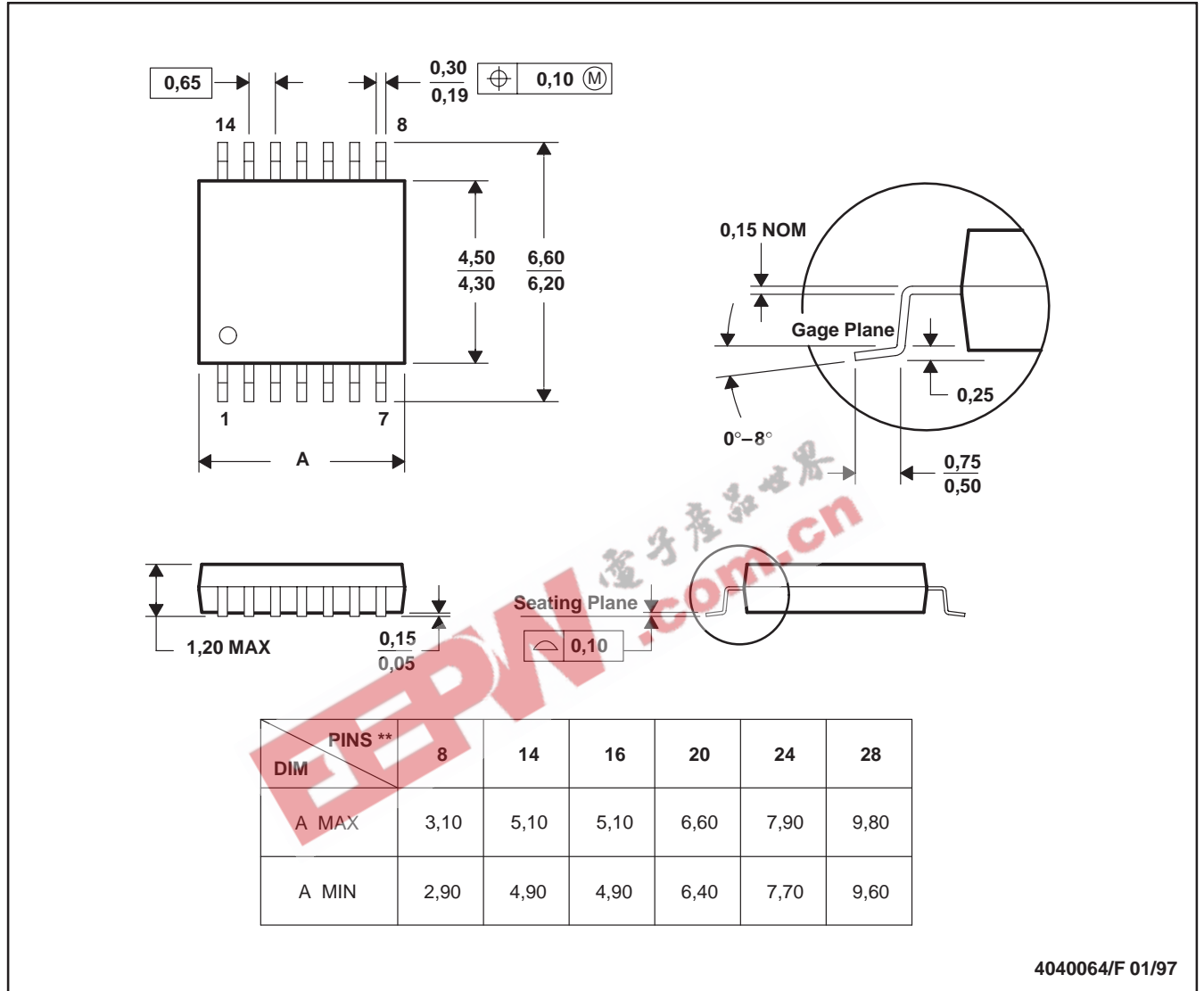
MECHANICAL DATA

MTSS001C – JANUARY 1995 – REVISED FEBRUARY 1999

PW (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

14 PINS SHOWN



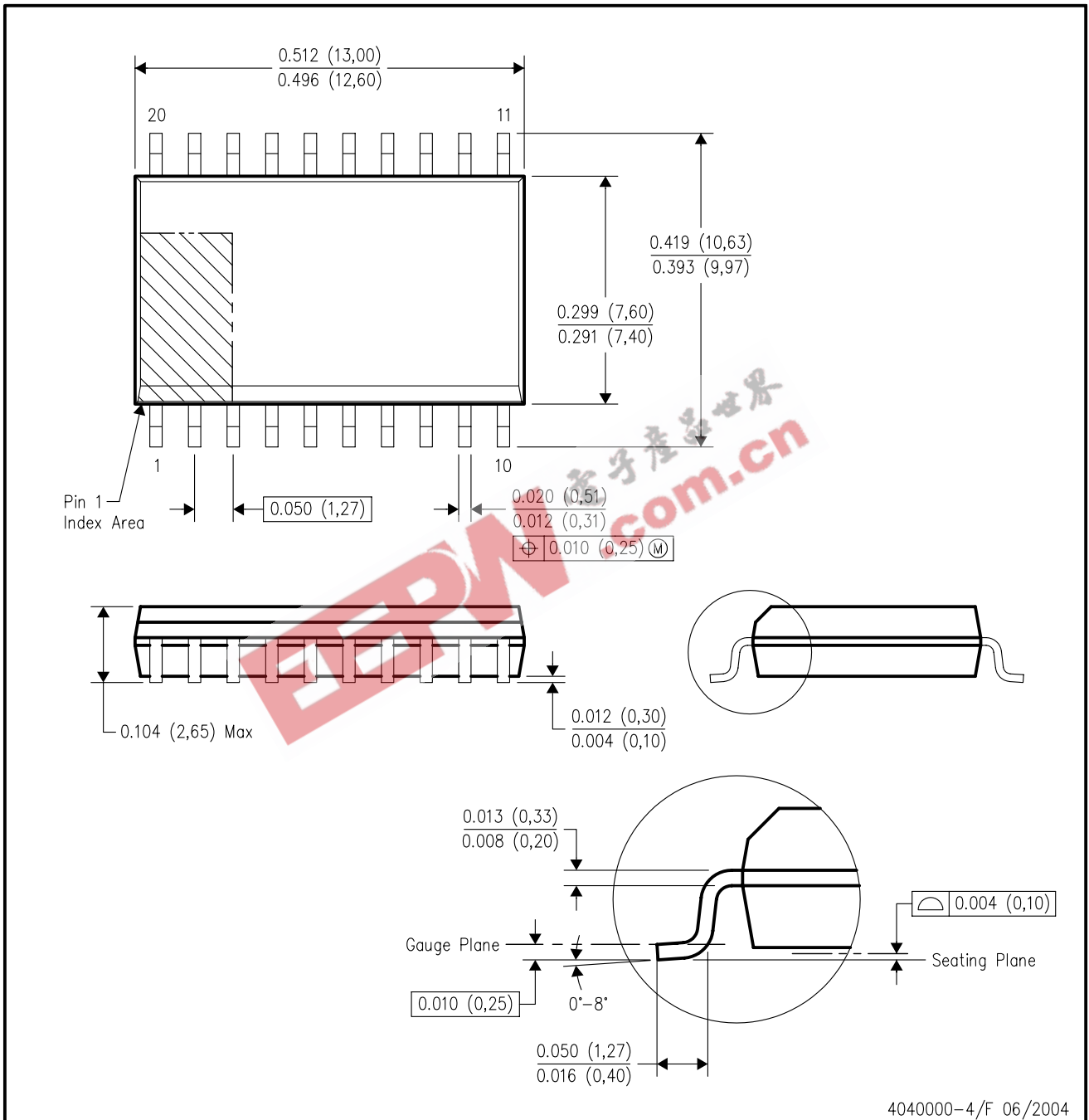
4040064/F 01/97

- NOTES: A. All linear dimensions are in millimeters.
 B. This drawing is subject to change without notice.
 C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.
 D. Falls within JEDEC MO-153

MECHANICAL DATA

DW (R-PDSO-G20)

PLASTIC SMALL-OUTLINE PACKAGE



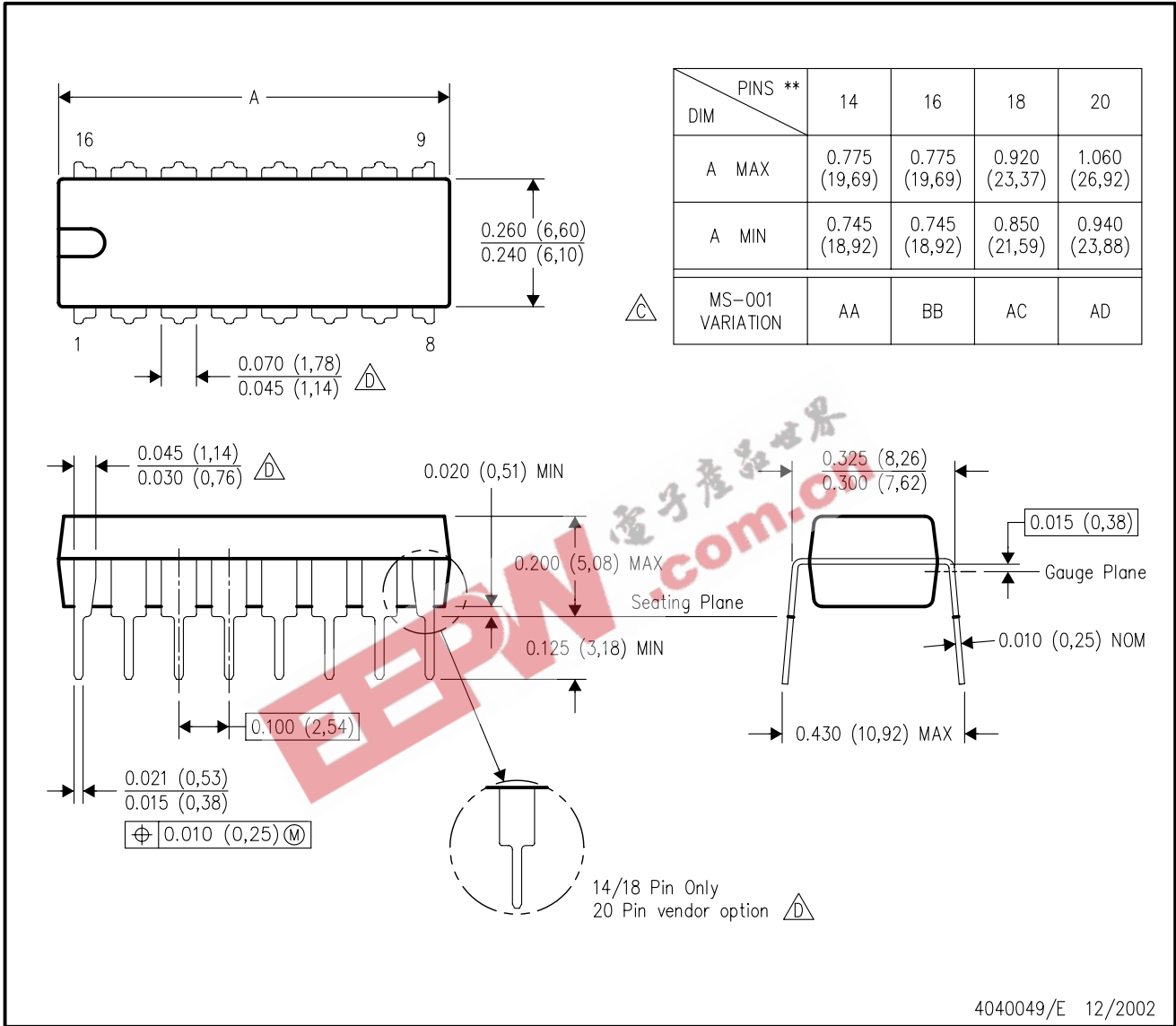
- NOTES:
- All linear dimensions are in inches (millimeters).
 - This drawing is subject to change without notice.
 - Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
 - Falls within JEDEC MS-013 variation AC.



MECHANICAL DATA

N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 -  Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
 -  The 20 pin end lead shoulder width is a vendor option, either half or full width.

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